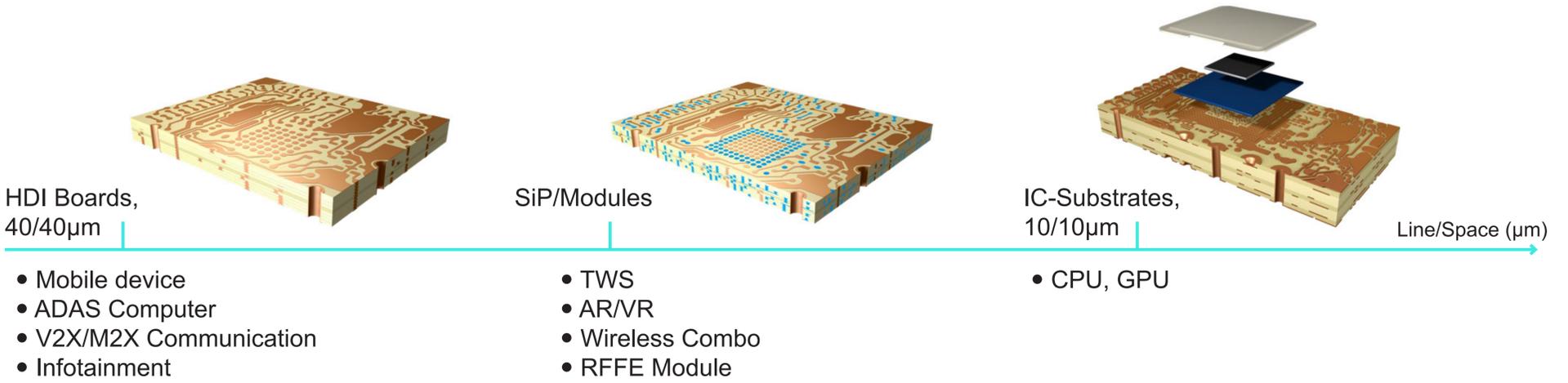


Miniaturization & Modularization

- High end HDI
- Fine line
- Size reduction
- BGA Fan Out
- Low Dk, Df, CTE material
- Warpage control

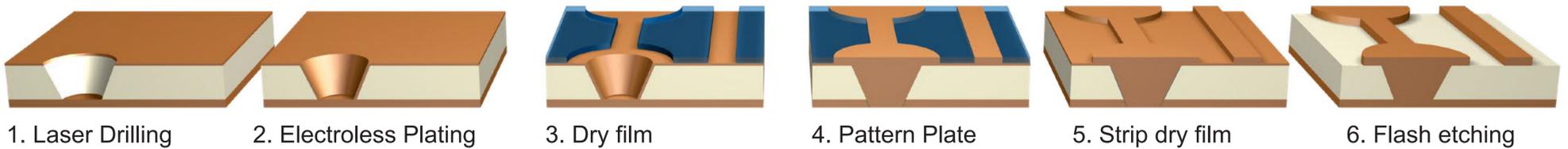
HDI board, SiP/Modules, IC-Substrates



mSAP vs. Subtractive - Capabilities

	Subtractive process	mSAP
Surface copper thickness	20 µm	15 µm
Laser pad size	180 µm	140 µm
Line width/spacing	40/40 µm	30/30 µm
Line geometry		
Copper roughness	4 µm	1.1 ~ 2 µm

mSAP Process



Subtractive Process

